

Unless otherwise defined, all capitalised terms and references used in this announcement shall have the meanings ascribed to them in the announcement dated 16 October 2018, the Offering Circular dated 3 August 2018 and the Pricing Supplement dated 16 October 2018

Temasek closes Public Offer of 2.70% 5-year T2023-S\$ Temasek Bond

- T2023-S\$ is first Temasek Bond with retail tranche
- Fixed interest rate of 2.70% per annum over 5 years
- Public Offer just over 8 times subscribed, with just over S\$1.6 billion of valid applications received
- Allocation basis will be announced by tomorrow evening

Singapore, 23 October 2018, 5.30pm – Temasek Holdings (Private) Limited (“**Temasek**”) refers to the announcement on Tuesday 16 October 2018 regarding the offer of the **T2023-S\$ Temasek Bond**, comprising up to S\$400 million 2.70% guaranteed notes due 2023 (subject to the Upsize Option), to be issued through its wholly-owned subsidiary Temasek Financial (IV) Private Limited.

Close of the Public Offer

The Public Offer closed on Tuesday 23 October 2018 at 12 noon.

As at the close of the Public Offer of up to S\$200 million, valid applications received totalled S\$1,675,700,000 representing a subscription rate of just over 8 times the Public Offer.

An allocation process will take place following the close of the Public Offer. The results of the allocation process will be announced by tomorrow evening.

Further information will be shared at that time on the listing and trading of the T2023-S\$ Temasek Bond on the SGX-ST, and the refunds of application monies for applications that were not successful.

This announcement will be posted on Temasek’s website at www.temasek.com.sg and on the website of the SGX-ST.

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